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BIB DATA SHEET

CONFIRMATION NO. 7930

SERIAL NUM	IBER	FILING or	371(c)		CLASS	GR	OUP ART	UNIT	ATTO	DRNEY DOCKET NO.	
10/018,18	88	12/18/2			451		3724		5	11.40998X00	
		RUL	E								
APPLICANTS Naoyuki Koyama, Ibaraki, JAPAN; Kouji Haga, Ibaraki, JAPAN; Masato Yoshida, Ibaraki, JAPAN; Keizou Hirai, Ibaraki, JAPAN; Toronosuke Ashizawa, Ibaraki, JAPAN; Youiti Machii, Ibaraki, JAPAN; ** CONTINUING DATA **********************************											
This application is a 371 of PCT/JP00/03891 06/15/2000											
** FOREIGN APPLICATIONS ************************************											
** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **											
Foreign Priority claimed Yes No 35 USC 119(a-d) conditions met Yes No Met after Allowance					STATE OR COUNTRY		SHEETS TOT RAWINGS CLAI			INDEPENDENT CLAIMS	
Verified and	/TIMOTHY Examiner's	V ELEY/	tve Initials	ince	JAPAN			12	<u>,</u>	2	
ADDRESS											
Antonelli Terry Stout & Kraus Suite 1800 1300 North Seventeenth Street Arlington, VA 22209 UNITED STATES											
TITLE											
Abrasive compound for cmp, method for polishing substrate and method for manufacturing semiconductor device using the same, and additive for cmp abrasive compound											
	FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following:						☐ All Fees				
							☐ 1.16 Fees (Filing)				
							☐ 1.17 Fees (Processing Ext. of time)				
							☐ 1.18 Fees (Issue)				
							Other				
							☐ Credit				